



QUALCOMM

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Mr. Mirko Cano
Ms. Susanna Kooistra
ETSI, MCC
650, route des Lucioles
06921 Sophia-Antipolis
France

Subject: Nomination of candidate for the 3GPP TSG SA WG3 Vice-Chairman

Dear Mr. Cano and Ms. Kooistra:

I am pleased to inform you that Qualcomm, through its ATIS 3GPP affiliation, is nominating Adrian Escott as a candidate for the position of 3GPP TSG SA WG3 Vice-Chairman at the upcoming election in SA3#81.

Adrian will be trained to comply with all applicable antitrust/competition laws and regulations while acting in his capacity as TSG SA WG3 Vice Chairman.

In proposing Adrian for the position of 3GPP TSG SA WG3 Vice-Chairman, Qualcomm will fully support Adrian in the vice-chairmanship role. Qualcomm remains fully committed to the success of 3GPP and its diverse ecosystem.

A brief curriculum vitae of Adrian is attached.

Best Regards,

A handwritten signature in black ink, appearing to read "Edward G. Tiedemann, Jr.", with a stylized flourish at the end.

Edward G. Tiedemann, Jr.
Senior Vice-President, Engineering
QUALCOMM Technologies, Inc.

Adrian Escott

Adrian graduated in 1990 with a BA in Mathematic from the University of Oxford and also obtained a PhD from Royal Holloway, University on London in 1994.

Adrian has been working at Qualcomm since 2005. He initially worked in the 3GPP2 standards team and was chair of 3GPP2 security group for some time. Since early 2007, he has been the Qualcomm lead representative in SA WG3. During this time, he has been heavily involved in the work of SA WG3 and has been rapporteur for several work items in SA WG3, e.g. Relay Nodes and the ProSe security work.